



Attorney's Docket No. 038190/241788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Slemmons et al.

Appl. No.: 10/005,633

Filed: December 5, 2001

For: MICROBEAM ASSEMBLY  
FOR INTEGRATED CIRCUIT  
INTERCONNECTION TO SUBSTRATES

Confirmation No.: 9245

Group Art Unit: 2827

Examiner: D. Graybill

March 18, 2003

Commissioner for Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-identified patent application as follows:

In The Claims:

Please cancel Claim 30 and please amend Claims 25 and 26 as follows:

25. A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:  
a carrier;  
a release layer located on said carrier, said release layer being etchable; and  
a plurality of conductive microbeams releasably bonded to said release layer, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein said microbeams are releasable from said carrier by at least partially etching away said release layer.

26. A microbeam assembly according to Claim 25 wherein the carrier is a tape automated bonding (TAB) carrier and said release layer is formed from a material selected from the group consisting of polyimide and parylene.

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